

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
20 July 2006 (20.07.2006)

PCT

(10) International Publication Number
WO 2006/076392 A3

(51) International Patent Classification:

C09K 13/00 (2006.01) **C09K 13/06** (2006.01)
C09K 13/04 (2006.01) **H01L 21/302** (2006.01)

(21) International Application Number:

PCT/US2006/000892

(22) International Filing Date: 10 January 2006 (10.01.2006)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

11/032,717 11 January 2005 (11.01.2005) US

(71) Applicant: **CLIMAX ENGINEERED MATERIALS, LLC** [US/US]; One North Central Avenue, Phoenix, Arizona 85004 (US).

(72) Inventors: **JHA, Sunil, Chandra**; 1695 W. Windgate Place, Oro Valley, Arizona 85737 (US). **NIMMALA, Sreehari**; 9901 N. Oracle Road, #1201, Oro Valley, Arizona 85737 (US). **HEGDE, Sharath**; 6757 State Highway #56, Apt. #7, Potsdam, New York 13676 (US). **BABU, S., V.**; 24 Haggerty Road, Potsdam, New York 13676 (US). **PATRI, Udaya, B.**; 6757 State Highway #56, Apt. #5, Potsdam, New York 13676 (US). **HONG, Youngki**; 102 Swan Street, Potsdam, New York 13676 (US).

(74) Agents: **DAHL, Bruce, E.** et al.; Dahl & Osterloth, LLP, 555 17th Street, Suite 3405, Denver, Colorado 80202 (US).

(81) Designated States (*unless otherwise indicated, for every kind of national protection available*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

- *with international search report*
- *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

(88) Date of publication of the international search report:
25 January 2007

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: POLISHING SLURRIES AND METHODS FOR CHEMICAL MECHANICAL POLISHING

(57) Abstract: Aqueous polishing slurries for chemical-mechanical polishing are effective for polishing copper at high polish rates. The aqueous slurries according to the present invention may include soluble salts of molybdenum dissolved in an oxidizing agent and molybdic acid dissolved in an oxidizing agent. Methods for polishing copper by chemical-mechanical planarization include polishing copper with low pressures using a polishing pad and a aqueous slurries including soluble salts of molybdenum dissolved in an oxidizing agent and molybdic acid dissolved in an oxidizing agent, particles of MoO₃ dissolved in an oxidizing agent, and particles of MoO₂ dissolved in an oxidizing agent.



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